25X Ø b Α В

D

С

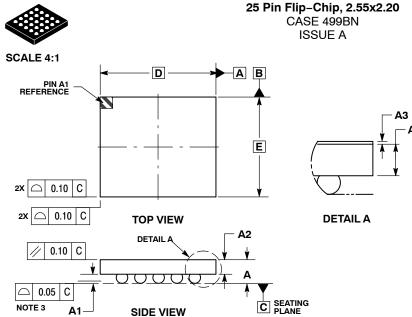
В

BOTTOM VIEW

0.05

С 0.03

#



DATE 26 OCT 2011

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.60	
A1	0.17	0.23	
A2	0.36 REF		
АЗ	0.04 REF		
b	0.24	0.29	
D	2.55 BSC		
Е	2.20 BSC		
е	0.40 BSC		

GENERIC MARKING DIAGRAM*



XXXXXX= Specific Device Code

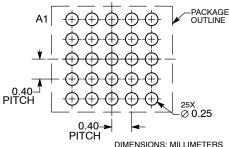
Α = Assembly Location

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	25 PIN FLIP-CHIP, 2.55X2.	20	PAGE 1 OF 1

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